



SEA & LAND ELECTRONIC CORP.

www.sealand-pptc.com

APPROVAL SHEET

MODEL NO.: SMD0603-010

CUSTOMER:

CUSTOMER'S APPROVAL:

AUTHORIZED SIGNATURE/STAMP:

DATE

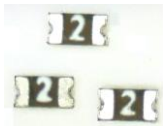
MANUFACTURER:

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Approved by: YC Lin
DATE: 2014/12/24

SEA & LAND ELECTRONIC CORP.



SMD0603-010

Features

- Surface Mount Devices
- Lead free device
- Size 1.5*0.8 mm / 0.06*0.03 inch
- Surface Mount packaging for automated assembly

Applications

- Almost anywhere there is a low voltage power supply, up to 15V and a load to be protected, including:
- Computer mother board, Modem, USB hub
 - PDAs & Charger, Analog & digital line card
 - Digital cameras, Disk drivers, CD-ROMs,

Performance Specification

Model	Marking	V _{max} (Vdc)	I _{max} (A)	I _{hold} @25°C (A)	I _{trip} @25°C (A)	P _d Typ. (W)	Maximum Time To Trip		Resistance	
							Current (A)	Time (Sec)	R _{i_min} (Ω)	R _{1_max} (Ω)
SMD0603-010	1	15.0	40	0.10	0.30	0.5	0.5	1.00	0.900	6.000

I_{hold} = Hold Current. Maximum current device will not trip in 25°C still air.
I_{trip} = Trip Current. Minimum current at which the device will always trip in 25°C still air.
V_{max} = Maximum operating voltage device can withstand without damage at rated current (I_{max}).
I_{max} = Maximum fault current device can withstand without damage at rated voltage (V_{max}).
P_d = Power dissipation when device is in the tripped state in 25°C still air environment at rated voltage.
R_{im}/max = Minimum/Maximum device resistance prior to tripping at 25°C.
R_{1_max} = Maximum device resistance is measured one hour post reflow.
CAUTION : Operation beyond the specified ratings may result in damage and possible arcing and flame.

Environmental Specifications

Test	Conditions	Resistance change
Passive aging	+85°C, 1000 hrs.	±5% typical
Humidity aging	+85°C, 85% R.H., 168 hours	±5% typical
Thermal shock	+85°C to -40°C, 20 times	±33% typical
Resistance to solvent	MIL-STD-202, Method 215	No change
Vibration	MIL-STD-202, Method 201	No change
Ambient operating conditions : - 40 °C to +85 °C		
Maximum surface temperature of the device in the tripped state is 125 °C		

AGENCY APPROVALS :

UL pending

Regulation/Standard:



2002/95/EC

EN14582

I_{hold} Versus Temperature

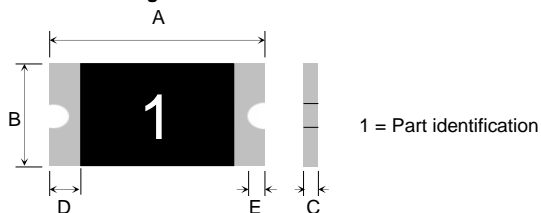
Model	Maximum ambient operating temperature (T _{mao}) vs. hold current (I _{hold})								
	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C
SMD0603-010	0.13	0.12	0.11	0.10	0.08	0.07	0.06	0.05	0.03

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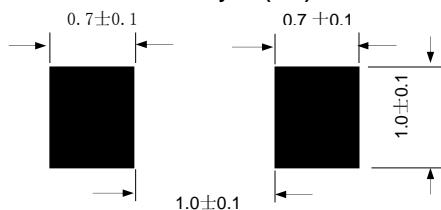
Construction And Dimension (Unit:mm)

Model	A		B		C		D		E
	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Min.	
SMD0603-010	1.45	1.85	0.65	1.05	0.40	1.00	0.15	0.10	

Dimensions & Marking



Recommended Pad Layout (mm)



Termination Pad Characteristics

Terminal pad materials :

Tin-plated Nickel-Copper

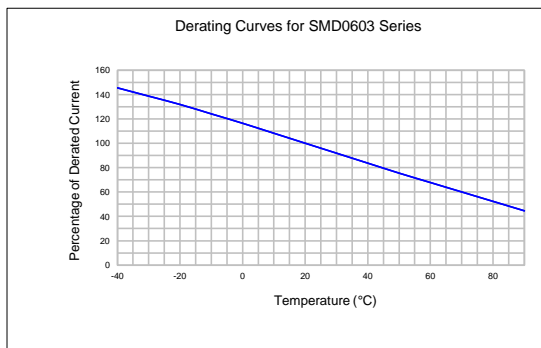
Terminal pad solderability :

Meets EIA specification RS186-9E and ANSI/J-STD-002 Category 3.

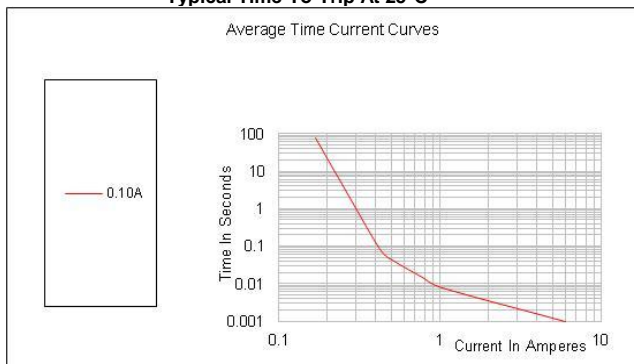
Rework

Use standard industry practices, the removal device must be replaced with a fresh one.

Thermal Derating Curve



Typical Time-To-Trip At 25°C

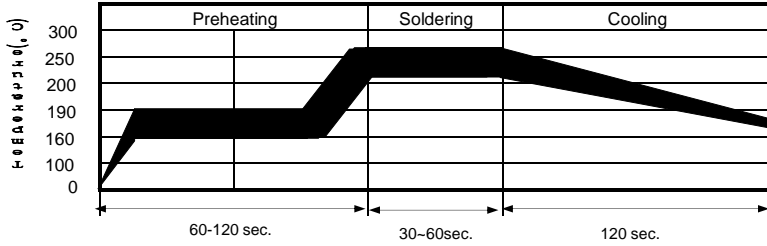


WARNING:

- Use PPTC beyond the maximum ratings or improper use may result in device damage and possible electrical arcing and flame.
- PPTC are intended for protection against occasional over current or over temperature fault conditions and should not be used when repeated fault conditions or prolonged trip events are anticipated.
- Device performance can be impacted negatively if devices are handled in a manner inconsistent with recommended electronic, thermal, and mechanical procedures for electronic components.
- Use PPTC with a large inductance in circuit will generate a circuit voltage ($L \cdot di/dt$) above the rated voltage of the PPTC.
- Avoid impact PPTC device its thermal expansion like placed under pressure or installed in limited space.
- Contamination of the PPTC material with certain silicon based oils or some aggressive solvents can adversely impact the performance of the devices. PPTC SMD can be cleaned by standard methods.
- Requests that customers comply with our recommended solder pad layouts and recommended reflow profile. Improper board layouts or reflow profile could negatively impact solderability performance of our devices.

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Recommended Solder Reflow Conditions



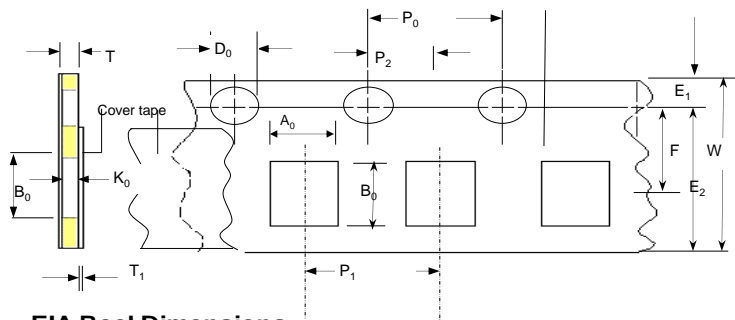
- Recommended reflow methods : IR, vapor phase oven, hot air oven.
- Devices are not designed to be wave soldered to the bottom side of the board.
- Recommended maximum paste thickness is 0.25 mm (0.010 inch).
- Devices can be cleaned using standard method and solvents.
- Note : If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Tape And Reel Specifications (mm)

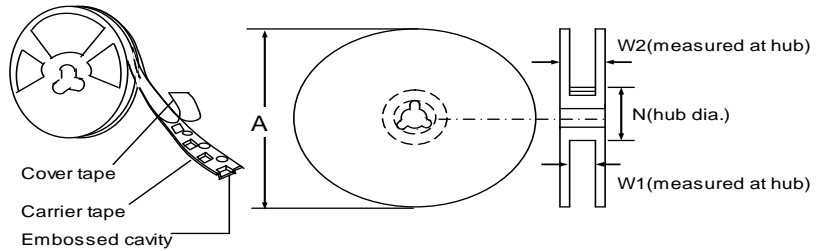
Governing Specifications

W	8.0 ± 0.2
P ₀	4.0 ± 0.10
P ₁	4.0 ± 0.10
P ₂	2.0 ± 0.05
A ₀	1.05 ± 0.10
B ₀	1.85 ± 0.10
D ₀	1.55 + 0.05
F	3.5 ± 0.05
E ₁	1.75 ± 0.10
E _{2min.}	6.25
T	0.75
T _{1max.}	0.1
K ₀	0.75/0.95 ± 0.1
Leader min.	390
Trailer min.	160
Reel Dimensions	
A max.	178
N min.	60
W ₁	9.0 ± 0.5
W ₂	12.0 ± 0.05

Paper Tape Component Dimensions



EIA Reel Dimensions



Storage And Handling

- Storage conditions : 40°C max, 70% R.H.
- Devices may not meet specified performance if storage conditions are exceeded.

Order Information

SMD0603	010	Packaging	Tape & Reel Quantity
Product name	Hold Current		
Size 1508 mm / 0603 inch	0.10A		5,000 pcs/reel
SMD: surface mount device			

Tape & reel packaging per EIA481-1

Labeling Information

Sea & Land Electronic Corp.

Model: **HF** **Pb** **RoHS**

Part no.:
Spec.:
Lot no.:
Q'ty:

倉儲: 密封! 溫度: 18~33°C/濕度: 30~60% A